



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts,Customers Priority,Honest Operation,and Considerate Service",our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

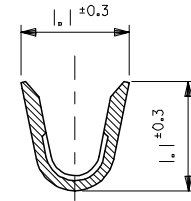
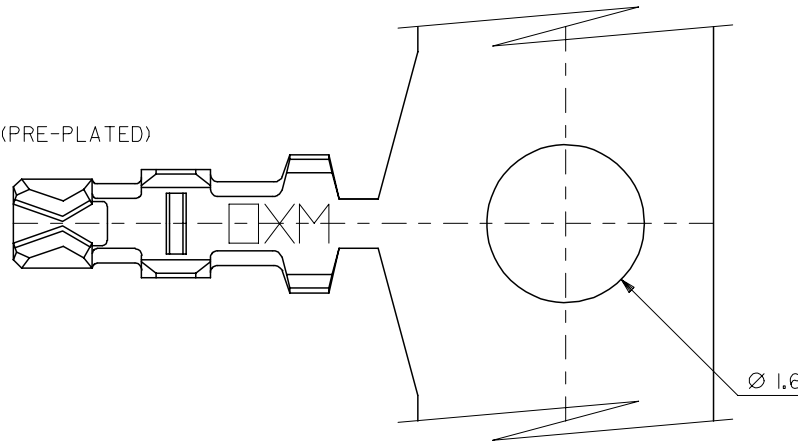
Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



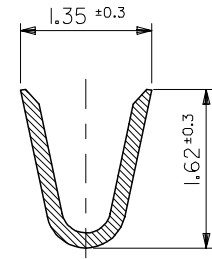
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注記
NOTES

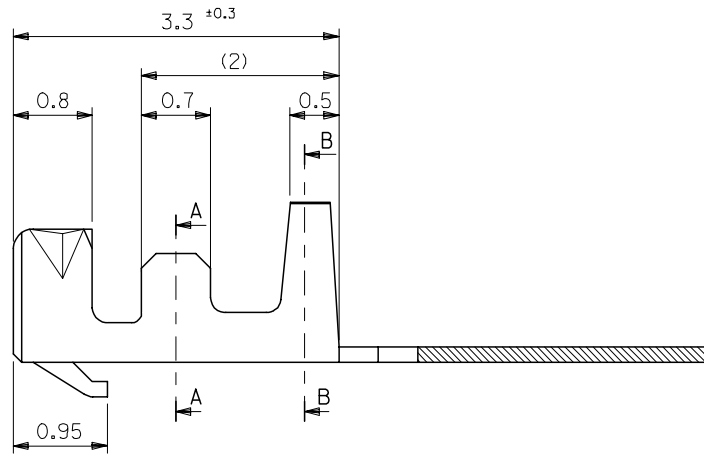
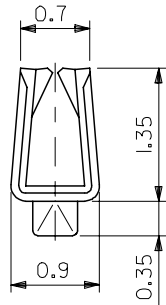
1. 適合ハウジング：51021シリーズ
APPLICABLE HOUSING : 51021 SERIES
2. メッキ仕様 PLATING
錫 0.9μm MIN. リフロー処理 (前メッキ)
TIN 0.9μm MIN. REFLOW TREATMENT (PRE-PLATED)



SECT. A-A



SECT. B-B



50079-8100	バラ状 LOOSE
50079-8000	連鎖状 CHAIN
MATERIAL NO.	端子形状 FORM

MODEL NO. 50079-8*00

材料 MATERIAL	リン青銅 (t=0.15) PHOSPHOR BRONZE
仕上げ FINISH	—#—
適用電線範囲 WIRE RANGE	AWG #26-28
被覆外径 INS. RANGE	$\varnothing 0.5-1.04$

REVISED	EC NO: J2005-1535	2004/11/30
DRAWN	DRW:SESUZUKI	2004/11/30
CHKD	CHKD:KTOJO	2004/11/30
APPD	APPD:NUKITA	2004/12/06
REV	G	

GENERAL TOLERANCES (UNLESS SPECIFIED)	
10 UNDER	± 0.2
10 OVER 30 UNDER	± 0.25
30 OVER	± 0.3
ANGULAR	$\pm 3^\circ$
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	

DIMENSION STYLE MM ONLY	
DRAWN BY HHIRAMOT	DATE 92/10/21
CHECKED BY SKUNISHI	DATE 98/07/07
APPROVED BY MFUKUSHI	DATE 98/07/07
MATERIAL NO.	
SIZE A3	

SCALE 20:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
TITLE 1.25 WIRE TO BOARD CONN. CRIMP REC. TERMINAL -LEAD FREE-		
MOLEX INCORPORATED		
DOCUMENT NO. SD-50079-001	SHEET NO. 1 OF 1	
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		

10 9 8 7 6 5 4 3 2 1

F

F

E

E

D

D

C

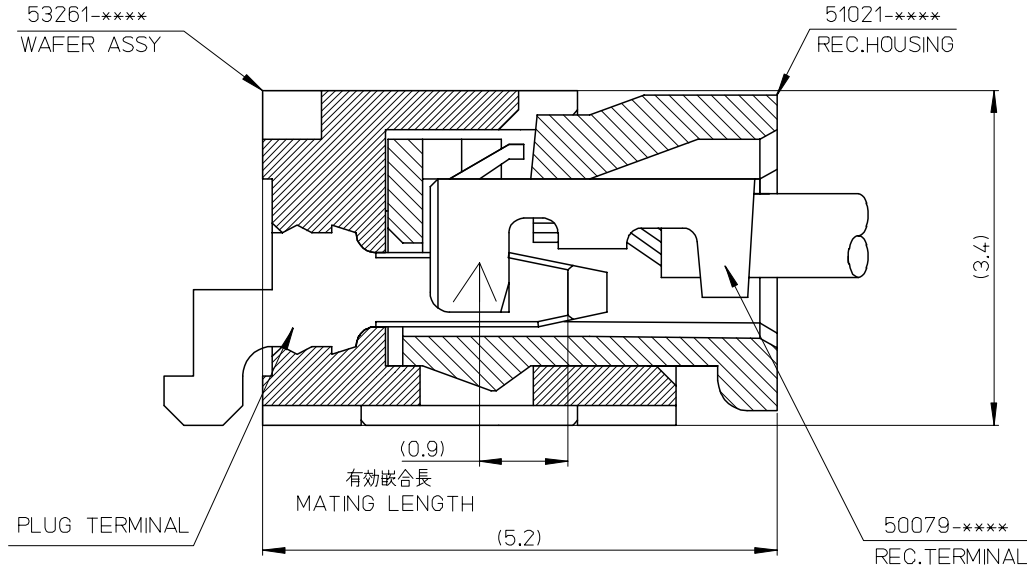
C

B

B

A

A



53261-****	WAFER ASSY	MODEL NO./MATERIAL NO.
50079-****	TERMINAL	
51021-****	HOUSING	

RELEASED EC NO: J2006-2426 DRWN: A0YAGI 2006/02/02 CHKD: YMAEDA 2006/02/03 APPR: NUKITA 2006/02/07	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
	10 UNDER	± ---	DRAWN BY Y. A0YAGI	DATE 2006/01/30	TITLE 1.25 W-TO-B CONN. 51021,53261 MATING CROSS SECTION				
	10 OVER 30 UNDER	± ---	CHECKED BY Y. MAEDA	DATE 2006/01/30	MOLEX INCORPORATED				
	30 OVER	± ---	APPROVED BY N. UKITA	DATE 2006/01/30	MATERIAL NO. SEE CHART		DOCUMENT NO. SD-51021-002	SHEET NO. 1 OF 1	
	ANGULAR	± --- °	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION						
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS									